

## ABSTRACT OF THE DISCLOSURE

An apparatus and methods for providing gross location, planarization, and mechanical restraint to one or more electronic components such as semiconductor dice to be subjected to stereolithographic processing. A double platen assembly including a first platen and a second platen mutually removably connected and configured and arranged to substantially secure an electronic component assembly in position therebetween. At least one of the platens is configured such that a portion of electronic components of a carrier substrate secured by the double platen assembly is viewable for exposure to an energy beam such as a laser beam used to cure a liquid into an associated dielectric stereolithographic packaging structure. Another embodiment includes the use of an adhesive-coated film for holding, locating and securing a plurality of individual electronic components for processing. A method of forming solder balls is also disclosed.

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